

# NAND-Flash Code Information(1/3)

Last Updated : Oct. 2005

**K** **9** X X X X X X X X - X X X X X X X  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 1. Memory (K)

2. NAND Flash : 9

## 3. Small Classification

(SLC : Single Level Cell, MLC : Multi Level Cell,

SM : SmartMedia, S/B : Small Block)

1 : SLC 1 Chip XD Card

2 : SLC 2 Chip XD Card

4 : SLC 4 Chip XD Card

A : SLC + Muxed I/ F Chip

B : Muxed I/ F Chip

D : SLC Dual SM

E : SLC DUAL (S/ B)

F : SLC Normal

G : MLC Normal

H : MLC QDP

J : Non-Muxed One Nand

K : SLC Die Stack

L : MLC DDP

M : MLC DSP

N : SLC DSP

Q : 4CHIP SM

R : SLC 4DIE STACK (S/ B)

S : SLC Single SM

T : SLC SINGLE (S/ B)

U : 2 STACK MSP

V : 4 STACK MSP

W : SLC 4 Die Stack

## 4~5. Density

12 : 512M      16 : 16M      28 : 128M

32 : 32M      40 : 4M      56 : 256M

64 : 64M      80 : 8M      1G : 1G

2G : 2G      4G : 4G      8G : 8G

AG : 16G      BG : 32G      CG : 64G

DG : 128G      00 : NONE

## 6~7. Organization

00 : NONE

08 : x8

16 : x16

## 8. Vcc

A : 1.65V~3.6V

B : 2.7V(2.5V~2.9V)

C : 5.0V(4.5V~5.5V)

D : 2.65V(2.4V ~ 2.9V)

E : 2.3V~3.6V

R : 1.8V(1.65V~1.95V)

Q : 1.8V(1.7V ~ 1.95V)

T : 2.4V~3.0V

U : 2.7V~3.6V

V : 3.3V(3.0V~3.6V)

W : 2.7V~5.5V, 3.0V~5.5V

0 : NONE

## 9. Mode

0 : Normal

1 : Dual nCE & Dual R/ nB

4 : Quad nCE & Single R/ nB

5 : Quad nCE & Quad R/ nB

9 : 1st block OTP

A : Mask Option 1

L : Low grade

## 10. Generation

M : 1st Generation

A : 2nd Generation

B : 3rd Generation

C : 4th Generation

D : 5th Generation

Y : Partial NAND((2nd)

Z : Partial NAND(1st)

# NAND-Flash Code Information(2/3)

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<u>K</u>	<u>9</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17 18

## 11. "—"

### 12. Package

A : COB	B : TBGA
C : CHIP BIZ	D : 63-TBGA
E : TSOP1(LF,1217)	F : WSOP(LF)
G : FBGA	H : TBGA(LF)
I : ULGA (LF)	J : FBGA(LF)
K : TSOP1(1217)	L : LGA
M : TLGA	N : TLGA2
P : TSOP1(LF)	Q : TSOP2(LF)
R : TSOP2-R	S : SMART MEDIA
T : TSOP2	U : COB(MMC)
V : WSOP	W : WAFER
Y : TSOP1	

### 13. Temp

C : Commercial	I : Industrial
S : SmartMedia	
B : SmartMedia BLUE	
0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)	
3 : Wafer Level 3	

### 14. Bad Block

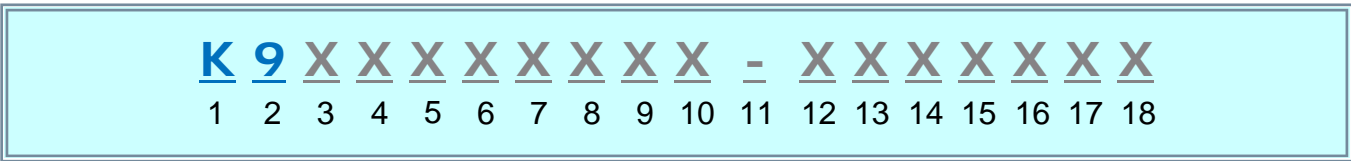
A : Apple Bad Block  
 B : Include Bad Block  
 D : Daisychain Sample  
 K : Sandisk Bin  
 L : 1~5 Bad Block  
 N : ini. 0 blk, add. 10 blk  
 S : All Good Block  
 0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)

### 15. NAND-Reserved

0 : Reserved

# NAND-Flash Code Information(3/3)

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## 16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
<b>Component</b>	TAPE & REEL	T
	Other ( Tray, Tube, Jar )	0 ( Number)
	Stack	S
<b>Component ( Mask ROM )</b>	TRAY	Y
	AMMO PACKING	A
<b>Module</b>	MODULE TAPE & REEL	P
	MODULE Other Packing	M

## 17~18. Customer "Customer List Reference"